

# Freescale Semiconductor, Inc.

Technical Data

MRFIC0970/D Rev. 0, 07/2002

3.2 V GSM GaAs Integrated Power Amplifier





# MRFIC0970



**Package Information** 

Plastic Package Case 1308 (QFN-20)

### **Ordering Information**

Device	Marking	Package
MRFIC0970	0970	QFN-20

The MRFIC0970 is a single supply, RF power amplifier designed for the 2.0 W GSM900 handheld radios. The device is packaged in the QFN-20 package, with exposed backside pad, which allows excellent electrical and thermal performance through a solderable contact.

• Target 3.2 V Characteristics:

RF Output Power: 34.5 dBm Typical

Efficiency: 50% Typical

- Single Positive Supply Solution
- Available in Tape and Reel only. R2 Suffix = 2500 Units per 12 mm, 13 inch Reel

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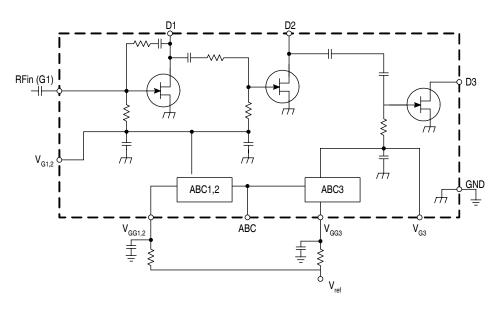


Figure 1. Functional Block Diagram

### 1 Electrical Characteristics

**Table 1. Maximum Ratings** 

Rating	Symbol	Value	Unit
Supply Voltage	V <sub>D1,2,3</sub> , V <sub>abc</sub> V <sub>ref</sub>	8.0 5.0	V V
RF Input Power	P <sub>in</sub>	15	dBm
RF Output Power	P <sub>out</sub>	38	dBm
Operating Case Temperature Range	T <sub>C</sub>	-40 to 85	°C
Storage Temperature Range	T <sub>stg</sub>	-40 to 85	°C
Junction Temperature	TJ	150	°C

NOTES: 1. Maximum Ratings are those values beyond which damage to the device may occur. Functional operation should be restricted to the limits in the Electrical Characteristics or Recommended Operating Conditions tables.

**Table 2. Recommended Operating Conditions** 

Characteristic	Symbol	Min	Тур	Max	Unit
Supply Voltage	V <sub>D1,2,3</sub> V <sub>abc</sub> V <sub>ref</sub>	2.8 0 0.04	- - -	5.5 5.5 1.8	Vdc V V
Input Power	P <sub>in</sub>	5.0	-	10	dBm

<sup>2</sup> ESD (electrostatic discharge) immunity meets Human Body Model (HBM) ≤250 V and Machine Model (MM) ≤60 V. This device is rated Moisture Sensitivity Level (MSL) 1. Additional ESD data available upon request.



# Freescale Semiconductor, Inc. Electrical Characteristics

### **Table 3. Electrical Specifications**

 $(V_{D1,2,3} = 3.2 \text{ V}, V_{abc} = 2.6 \text{ V}, P_{in} = 5.0 \text{ dBm}, Peak measurement at 12.5\% duty cycle, 4.6 ms period, } T_A = 25 ^{\circ}C, unless otherwise noted.)$ 

Characteristic	Symbol	Min	Тур	Max	Unit
Frequency Range	BW	880	-	915	MHz
Output Power	P <sub>out</sub>	34.5	-	-	dBm
Power Added Efficiency	PAE	50	-	-	%
Minimum Output Power (V <sub>ref</sub> = 0.04, V <sub>abc</sub> = 2.6 V)		-	-	-17	dBm
Power Control Slope ( $V_{ref} = 0.1 \text{ to } 1.8 \text{ V}, \Delta V_{ref} = 0.01 \text{ V}$ )		-	-	50:1	RFVrms /V <sub>ref</sub>
Bleed thru Power ( $P_{in(fo)} \le -12dBm$ , $V_{ref} = 0.04$ , $V_{abc} = 10 \text{ k load}$ )		-	-	-36	dBm
RF Leakage Current ( $I_{DD1} + I_{DD2} + I_{DD3}$ , Pin ( $f_o$ ) $\leq$ 5.0 dBm) ( $V_{abc}$ = 10 k load, $V_{ref}$ = 0.04 V)		-	-	35	mA
Output Power Switching Speed (± step input of V <sub>ref</sub> RF Pout within 1.0 dB of final value)		-	-	1.0	μs
Input Return Loss	S11	-	-	6.0	dB
Noise Power in Rx band 925 to 935 MHz 935 to 960 MHz	NP	-		-73 -85	dBm
Stability-Spurious Output (Load VSWR 6:1 all phase angles, Adjust V <sub>D1, 2&amp;3</sub> for specified power)	P <sub>spur</sub>	-	-	-30	dBc
Load Mismatch Stress (Load VSWR = 10:1 all phase angles, 5 seconds, Adjust V <sub>D1, 2&amp;3</sub> for specified power)	No Degradation in Output Power Before & After Test				



# 2 Pin Connections

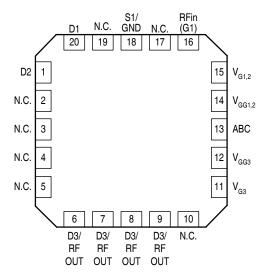


Figure 2. Pin Connections

# 3 Typical Performance Characteristics

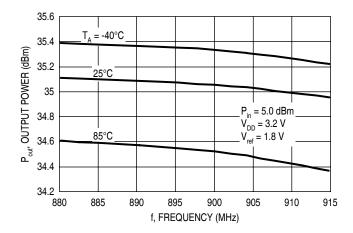


Figure 3. Output Power versus Frequency



# Freescale Semiconductor, Inc. Typical Performance Characteristics

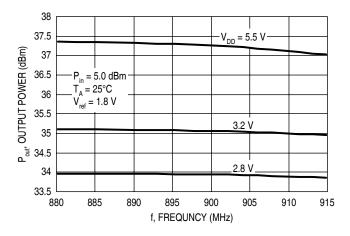


Figure 4. Output Power versus Frequency

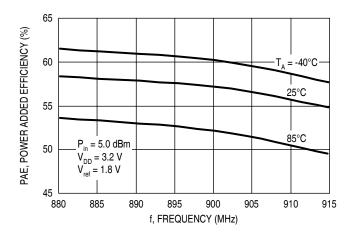


Figure 5. Power Added Efficiency versus Frequency

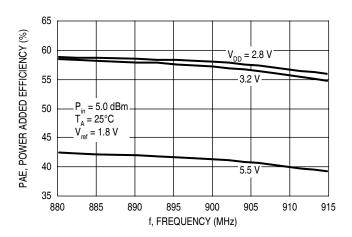


Figure 6. Power Added Efficiency versus Frequency



# 4 Application Schematic

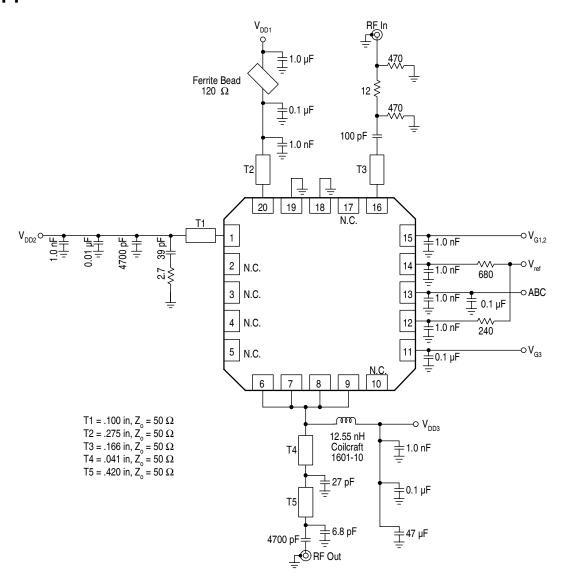


Figure 7. Application Schematic



# 5 Packaging

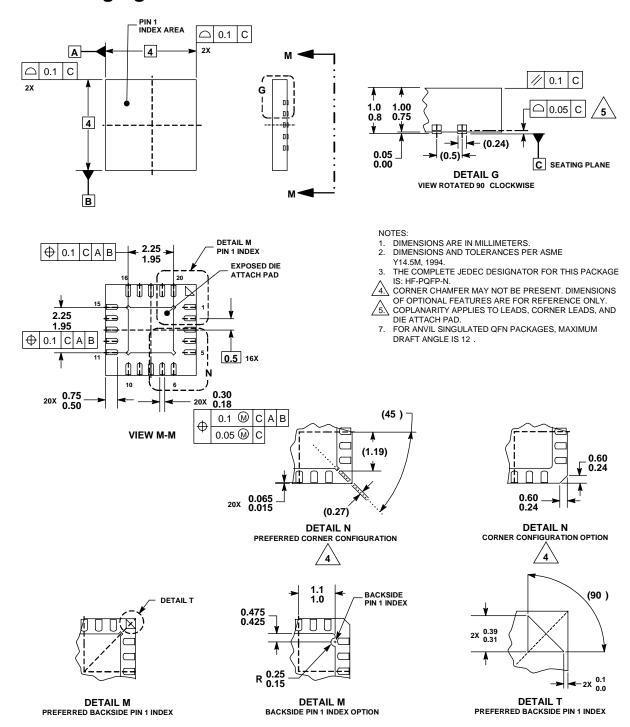


Figure 8. Outline Dimensions for QFN-20 (Case 1308-02, Issue C)



### Freescale Semiconductor, Inc.

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